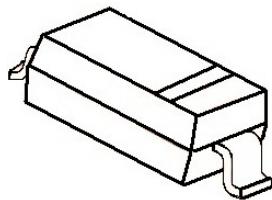


SD103AW/SD103BW/SD103CW

SOD-123



Marking: SD103AW: S4
SD103BW: S5
SD103CW: S6

SOD-123 贴片塑封肖特基二极管

SOD-123 Plastic-Encapsulate Schottky Barrier Diode

特征 Features

- 大电流承受能力。High Current Capability
- 正向压降低。Low Forward Voltage Drop

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性($TA = 25^\circ\text{C}$ 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	SD103AW	SD103BW	SD103CW	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	VRRM	40	30	20	V
最大均方根电压 Maximum RMS voltage	VRMS	28	21	14	V
最大直流阻断电压 Maximum DC blocking voltage	VDC	40	30	20	V
最大正向平均整流电流 Maximum average forward rectified current	IFM	350			mA
峰值正向浪涌电流 8.3ms 单一正弦半波 Peak forward surge current 8.3 ms single half sine-wave	IFSM	2			A
功率消耗 Power Dissipation	PD	400			mW
典型热阻 T Typical thermal resistance	R _{θJA}	250			°C/W
工作结温 Operating junction temperature	T _j	125			°C
存储温度 Storage temperature range	T _{STG}	-50~+150			°C

电特性 ($TA = 25^\circ\text{C}$ 除非另有规定)

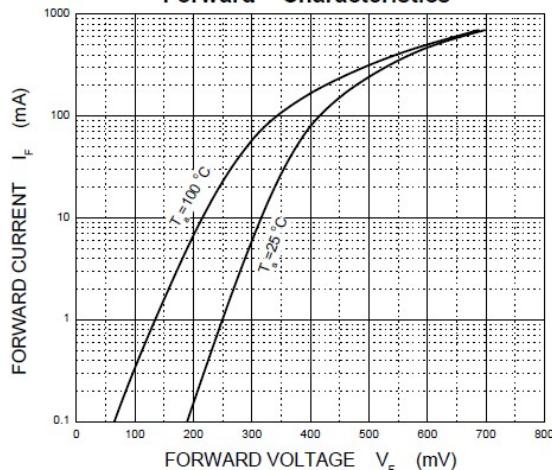
Electrical Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	测试条件 Test conditions	SD103AW	SD103BW	SD103CW	单位 Unit
最大正向电压 Maximum forward voltage	V _F	IF = 20mA IF = 200mA	0.370 0.600			V
最大反向电流 Maximum reverse breakdown voltage	I _R	I _R =100uA	40	30	20	V
最大反向电流 Maximum reverse current	I _R	VR=30V SD103AW VR=20V SD103BW VR=10V SD103CW	5.0			uA
典型结电容 Type junction capacitance	C _j	VR =0V, f = 1MHz	50			pF
反向恢复时间 Reverse recovery time	T _{rr}	IF=IR=200mA, I _{rr} =0.1xI _R ,RL=100 Ω	10			ns

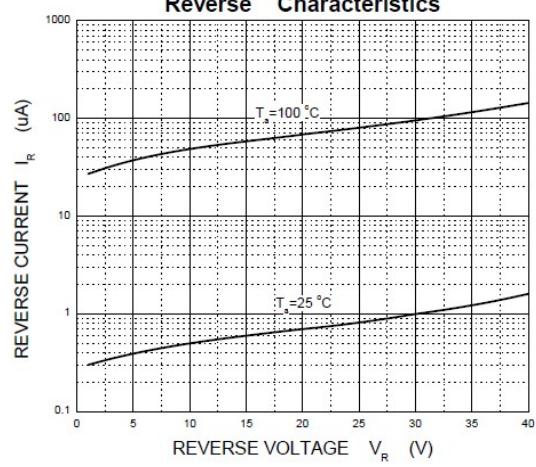
SD103AW/SD103BW/SD103CW

特性曲线Characteristic Curves

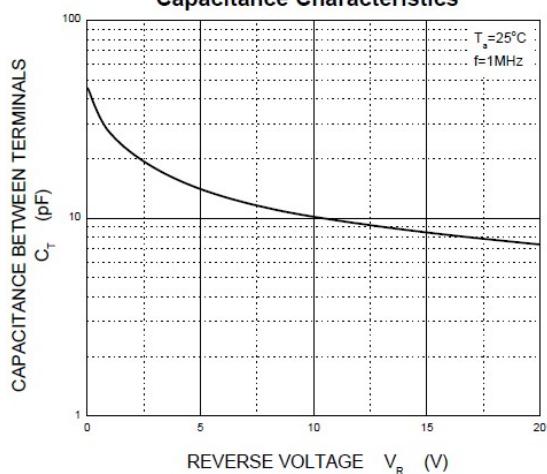
Forward Characteristics



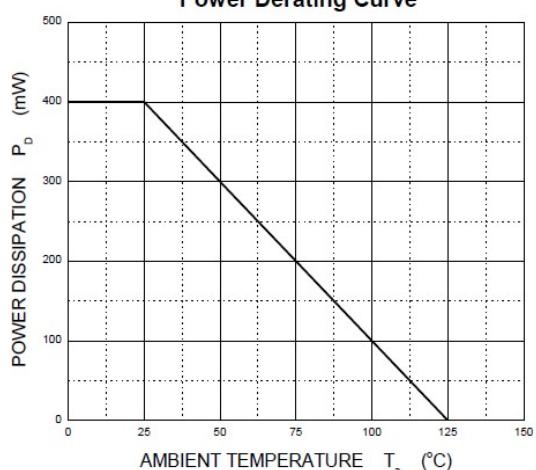
Reverse Characteristics



Capacitance Characteristics



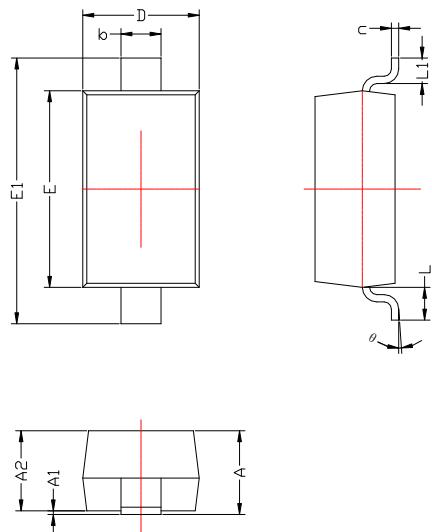
Power Derating Curve



SD103AW/SD103BW/SD103CW

SOD-123 PACKAGE OUTLINE

Plastic surface mounted package

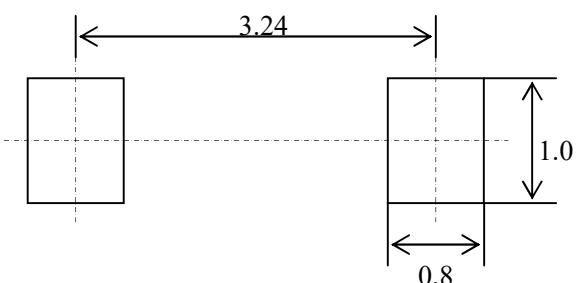


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



技术要求:

- 中心距: 3.24
脚 宽: 0.55
焊盘宽: 1.00
脚 长: 0.50
焊盘长: 0.80
- 1, 塑封体尺寸: 2.70 X 1.60
2: 未注公差为: ±0.05
3, 所有单位: mm